

Docket No.: 240627US0/tma

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RE APPLICATION OF: Yoshifumi INOUE

SERIAL NUMBER: 10/625,512

GROUP: 1712

FILED: July 24, 2003

EXAMINER: ROBERTSON, JEFFREY

FOR: FLAME RETARDANT EPOXY RESIN COMPOSITION, SEMICONDUCTOR
ENCAPSULATING MATERIAL USING SAME, AND RESIN ENCAPSULATED
SEMICONDUCTOR DEVICE

REQUEST TO CORRECT ALLOWED CLAIMS

MAIL STOP ISSUE FEE
COMMISSIONER FOR PATENTS
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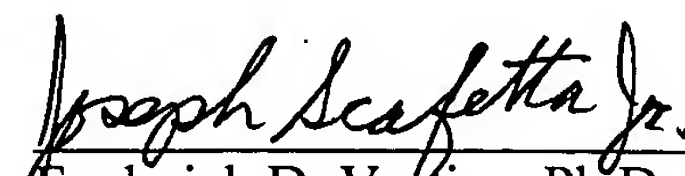
SIR:

In the matter of the above-identified application for patent, we hereby request
correction of your records to reflect the correct allowed claims.

The allowed claims should be: 19-20, 22, 24, 26-27, 29-30, 32 and 35-40.

Respectfully Submitted,

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OSMM&N File No. 240627US0

Serial No. 10/625,512

In the matter of the Application of: Yoshifumi INOUE

For: FLAME RETARDANT EPOXY RESIN COMPOSITION, SEMICONDUCTOR
ENCAPSULATING MATERIAL USING SAME, AND RESIN
ENCAPSULATED SEMICONDUCTOR DEVICE

Dept.. Chemical

By: NFO/FDV/esw

Due Date: 05/01/06

The following has been received in the U.S. Patent Office on the date stamped hereon

- Dep. Acct. Order Form
- PTO Cover Letter
- Amendment under 37 CFR 1.312



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